



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE8080EM			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000999758							
<b>Package</b>	PG-SSOP-24-9			<b>Weight*</b>	150.89 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.456	2.29	2.29	22902	22902
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8914	
wire	non noble metal	copper	7440-50-8	54.617	36.20	37.14	361964	371435
	non noble metal	copper	7440-50-8	0.866	0.57	0.57	5740	5740
	organic material	carbon black	1333-86-4	0.173	0.11		1145	
encapsulation	plastics	epoxy resin	-	7.946	5.27		52659	
	inorganic material	silicondioxide	60676-86-0	78.249	51.86	57.24	518582	572386
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19292	19292
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.252	0.17		1673	
	noble metal	silver	7440-22-4	0.757	0.50	0.67	5019	6692
*deviation	< 10%			Sum in total:		100,00		1000000

### Important Remarks:

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